

Dual N-Channel 2.5-V (G-S) MOSFET Common Drain, ESD Protection

CHARACTERISTICS

- N-Channel Vertical DMOS
- Macro Model (Subcircuit Model)
- Level 3 MOS

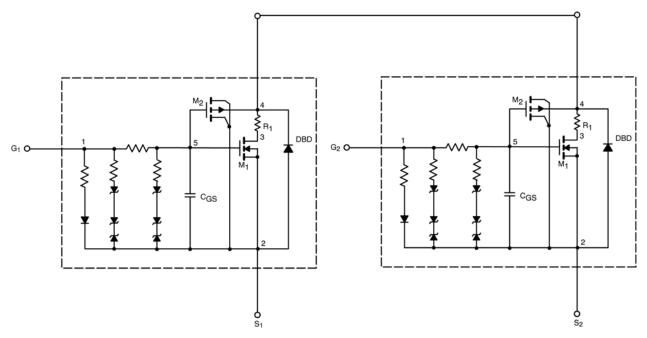
- Apply for both Linear and Switching Application
- Accurate over the –55 to 125°C Temperature Range
- Model the Gate Charge, Transient, and Diode Reverse Recovery Characteristics

DESCRIPTION

The attached spice model describes the typical electrical characteristics of the n-channel vertical DMOS. The subcircuit model is extracted and optimized over the -55 to 125° C temperature ranges under the pulsed 0-V to 5-V gate drive. The saturated output impedance is best fit at the gate bias near the threshold voltage.

A novel gate-to-drain feedback capacitance network is used to model the gate charge characteristics while avoiding convergence difficulties of the switched C_{gd} model. All model parameter values are optimized to provide a best fit to the measured electrical data and are not intended as an exact physical interpretation of the device.

SUBCIRCUIT MODEL SCHEMATIC



This document is intended as a SPICE modeling guideline and does not constitute a commercial product data sheet. Designers should refer to the appropriate data sheet of the same number for guaranteed specification limits.



SPECIFICATIONS (T _J = 25° C UI	NLESS OTHERV	VISE NOTED)			
Parameter	Symbol	Test Condition	Simulated Data	Measured Data	Unit
Static			•		
Gate Threshold Voltage	V _{GS(th)}	V_{DS} = V_{GS} , I_D = 250 μ A	1.1		V
On-State Drain Current ^a	I _{D(on)}	V_{DS} = 5 V, V_{GS} = 4.5 V	158		А
Drain-Source On-State Resistance ^a	r _{DS(on)}	V_{GS} = 4. 5V, I_{D} = 6.5 A	0.0163	0.0165	Ω
		V_{GS} = 2.5 V, I _D = 5.5 A	0. 0220	0.0230	
Forward Transconductance ^a	g _{fs}	V_{DS} = 10 V, I _D = 6.5 A	34	30	S
Forward Voltage ^a	V _{SD}	$I_{\rm S}$ = 1.5 A, $V_{\rm GS}$ = 0 V	0.68	0.71	V
Dynamic ^b					
Total Gate Charge	Qg	$V_{\rm DS}$ = 10 V, $V_{\rm GS}$ = 4.5 V, $I_{\rm D}$ = 6.5 A	12	12	nC
Gate-Source Charge	Q _{gs}		2.2	2.2	
Gate-Drain Charge	Q _{gd}		3.6	3.6	
Turn-On Delay Time	t _{d(on)}	$\label{eq:V_DD} \begin{array}{l} V_{\text{DD}} = 10 \ \text{V}, \ R_{\text{L}} = 10 \ \Omega \\ I_{\text{D}} \cong \ 1 \ \text{A}, \ V_{\text{GEN}} = 4.5 \ \text{V}, \ R_{\text{G}} = 6 \ \Omega \end{array}$	230	245	ns
Rise Time	tr		289	330	
Turn-Off Delay Time	t _{d(off)}		751	860	
Fall Time	t _f		692	510	

Notes

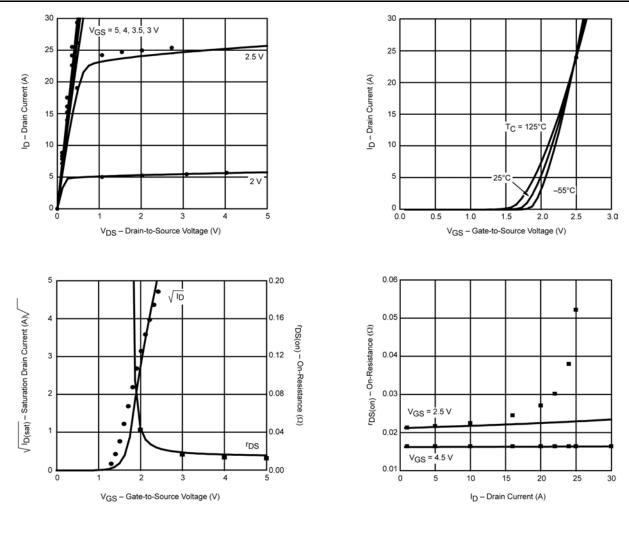
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2%. b. Guaranteed by design, not subject to production testing.

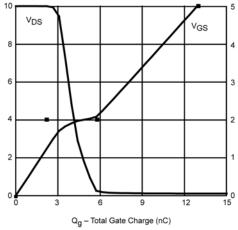


SPICE Device Model Si6968BEDQ

Vishay Siliconix

COMPARISON OF MODEL WITH MEASURED DATA (TJ=25°C UNLESS OTHERWISE NOTED)





Note: Dots and squares represent measured data.



Vishay

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